

Major Ratings and Characteristics

$I_F(MV)$	2.5A
V_{RRM}	1000V
I_{FSM}	50A
I_R	5uA
V_F	1.7V
T_{rr}	75ns
T_{jMAX}	150°C

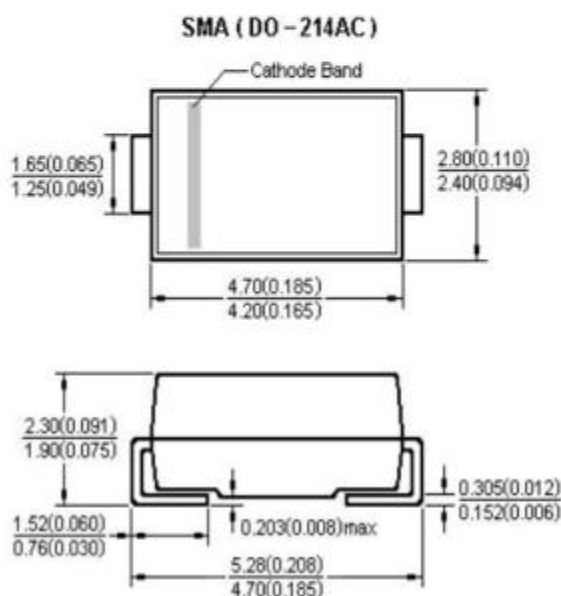
Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junctions
- Ultrafast reverse recovery time
- Low switching losses, high efficiency
- High forward surge capability
- High temperature soldering:
260°C/10 seconds at terminals
- Component in accordance to
RoHS 2002/95/1 and WEEE 2002/96/EC

Mechanical Date

- **Case:** JEDEC DO-214AC molded plastic body over passivated chip
- **Terminals:** Solder plated, solderable per J-STD-002B and JESD22-B102D

Surface Mount Standard Rectifiers



Dimensions in millimeters and (inches)

Maximum Ratings & Thermal Characteristics & Electrical Characteristics

(TA = 25 °C unless otherwise noted)

Type Number	SYMBOL	US3M	unit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS Voltage	V_{RMS}	700	V
Maximum DC blocking Voltage	V_{DC}	1000	V
Maximum Average Forward Rectified Current .at TA =55°C	$I_{F(AV)}$	2.5	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	I_{FSM}	50.0	A
Maximum Forward Voltage at 1.5A DC	V_F	1.7	V
Maximum DC Reverse Current @TA =25°C	I_R	5.0	μA
At rated DC blocking voltage @TA=100°C		100.0	
Typical Junction Capacitance (Note1)	C_j	15	pF
Maximum reverserecovery tme (Note2)	t_{rr}	75	ns
Typical Thermal Resistance (Note 2)	$R_{(JA)}$	75	°C /W
Storage Temperature	T_{STG}	-55 to +150	°C
Operation Junction Temperature	T_j	-55 to +150	°C

Characteristic Curves ($T_A=25\text{ }^{\circ}\text{C}$ unless otherwise noted)

Fig.1 Forward Current Derating Curve

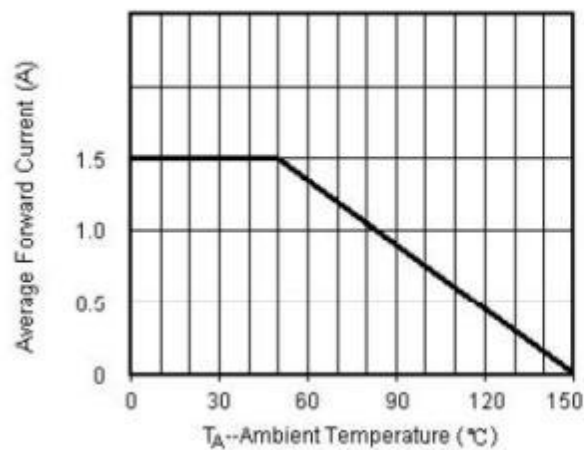


Fig.2 Maximum Non-Repetitive Peak Forward Surge Current

